



CBR-SMD RF COG, Ceramic, 2.4 pF, +/-0.05 pF, 50 VDC, COG, SMD, Fixed, RF, Ultra High Q, Low ESR, Class I, 0402



General Information		
Series	CBR-SMD RF COG	
Style	SMD Chip	
Description	SMD, Fixed, RF, Ultra High Q, Low ESR, Class I	
Features	Ultra High Q, Low ESR, Class I	
RoHS	Yes	
Termination	Tin	
Marking	No	
AEC-Q200	No	
Typical Component Weight	1.37 mg	
Notes	Solder Reflow Only.	
Shelf Life	78 Weeks	
MSL	1	

2.4 pF

+/-0.05 pF

Dimensions	
Chip Size	0402
L	1mm +/-0.05mm
W	0.5mm +/-0.05mm
Т	0.5mm +/-0.05mm
В	0.25mm +0.05/-0.1mm

VV	0.5mm +/-0.05mm	voltage DC	50 VDC	
Т	0.5mm +/-0.05mm	Dielectric Withstanding Voltage	125 VDC	
B 0.25mm +0.05/-0.1mm		Temperature Range -55/+125°C		
		Temp. Coefficient	COG	
Packaging Specifications		Dissipation Factor	0.223%	
Packaging	T&R, 180mm, Plastic Tape	Aging Rate	0% Loss/Decade	
Packaging Quantity 10000		Insulation Resistance	10 GOhms	

	0.5mm +/-0.05mm	Voltage DC	50 VDC
	0.5mm +/-0.05mm	Dielectric Withstanding Voltage	125 VDC
	0.25mm +0.05/-0.1mm	Temperature Range	-55/+125°C
		Temp. Coefficient	COG
ackaging Specifications		Dissipation Factor	0.223%
ackaging	T&R, 180mm, Plastic Tape	Aging Rate	0% Loss/Decade Hour
ckaging Quantity 10000	Insulation Resistance	10 GOhms	
		Quality Factor	448

**Specifications** 

Capacitance

Tolerance

Statements of suitability for certain applications are based on our knowledge of typical operating conditions for such applications, but are not intended to constitute - and we specifically disclaim - any warranty concerning suitability for a specific customer application or use. This Information is intended for use only by customers who have the requisite experience and capability to determine the correct products for their application. Any technical advice inferred from this Information or otherwise provided by us with reference to the use of our products is given gratis, and we assume no obligation or liability for the advice given or results obtained.

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